

ABSTRACT OF THE DISCLOSURE

There is disclosed a heating apparatus which has an electrostatic adsorption function and which comprises at least a supporting substrate, an electrode for electrostatic adsorption formed on a surface of one side of the supporting substrate, a heating layer formed on a surface of the other side of the supporting substrate, and an insulating layer formed so that it may cover the electrode for electrostatic adsorption and the heating layer wherein a volume resistivity of the insulating layer is varied in a plane. Thus, there can be provided a heating apparatus which has an electrostatic adsorption function wherein uniformity of a temperature distribution in a plane of the wafer when the wafer is heated can be improved, and the wafer can be heat-treated uniformly.